



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D <i>* : Required Field</i>

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2015-05-21
<b>Contact Name *</b>	Refer to "Supplier Comment" section	<b>Contact Title</b>	Refer to "Supplier Comment" section
<b>Contact Phone *</b>	Refer to "Supplier Comment" section	<b>Contact Email *</b>	Refer to "Supplier Comment" section
<b>Authorized Representative *</b>	Flavio Di Francesco	<b>Representative Title</b>	AMS Material Declaration Champion
<b>Representative Phone *</b>	Refer to "Supplier Comment" section	<b>Representative Email *</b>	Refer to "Supplier Comment" section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/internet/com/support/online_tech_support.jsp">http://www.st.com/internet/com/support/online_tech_support.jsp</a>		

**Uncertainty Statement**

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**Legal Statement**

<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard
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**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	IDO7*0081BE6	A	BO2A	2015-05-21
Amount	UoM	Unit type	ST ECOPACK Grade	
80.00	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3	 life.augmented	
bulk Solder Termination	Terminal Plating	Terminal Base Alloy		
Not Applicable ; if coating is used or other bulk termination : add in comments	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
D50	4.9 - 3.9 - 1.52	8	gull wing	
Comment	Package: SO 08 .15 JEDEC; MD valid for LF351DT - TL071ACDT - TL071CDT - LF351D - TL071IDT - TL081CDT - TL081IDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
Product(s) meets EU RoHS requirement without any exemptions	true
Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Product(s) is obsolete, no information is available	false
Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList :REACH-17 December 2014				
Query				Response
The product does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	IDO7*0081BE6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
die (s)	Other inorganic materials	0.977	mg	supplier	die	Silicon (Si)	7440-21-3		0.956	mg	978506	12497
die (s)				supplier	metallization	Aluminium (Al)	7429-90-5		0.012	mg	12282	157
die (s)				supplier	passivation	Silicon Nitride (SiN)	68034-42-4		0.004	mg	4094	52
die (s)				supplier	passivation	Silicon Oxide(SiO2)	7631-86-9		0.005	mg	5118	65
Leadframe	Copper & its alloys	35.078	mg	supplier	alloy	Copper (Cu)	7440-50-8		33.855	mg	965135	442549
Leadframe				supplier	alloy	Iron (Fe)	7439-89-6		0.796	mg	22692	10405
Leadframe				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.048	mg	1368	627
Leadframe				supplier	alloy	Zinc (Zn)	7440-66-6		0.042	mg	1197	549
Leadframe				supplier	metallization	Nickel (Ni)	7440-02-0		0.313	mg	8923	4092
Leadframe				supplier	metallization	Palladium (Pd)	7439-89-6		0.013	mg	371	170
Leadframe				supplier	metallization	Gold (Au)	12185-10-3		0.011	mg	314	144
Die attach	Other inorganic materials	0.412	mg	supplier	glue or tape	Silver (Ag)	7440-22-4		0.375	mg	910194	4902
Die attach				supplier	glue or tape	acrylate	na		0.021	mg	50971	275
Die attach				supplier	glue or tape	Methacrylate	na		0.016	mg	38835	209
Bonding wire	Other inorganic materials	0.032	mg	supplier	wire	Copper (Cu)	7440-50-8		0.032	mg	1000000	418
encapsulation	Other inorganic materials	43.501	mg	supplier	mold compound	Epoxy Resin	na		3.263	mg	75010	42654
encapsulation				supplier	mold compound	Phenol Resin	na		2.175	mg	49999	28431
encapsulation				supplier	mold compound	Silica, vitreous	60676-86-0		37.671	mg	865980	492431
encapsulation				supplier	mold compound	Carbon black	1333-86-4		0.218	mg	5011	2850
encapsulation				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.174	mg	4000	2275